

8 24-00



09-05-2000



101449081

PATENT  
0819-0363

To the Honorable Commissioner of Patents

Please record the attached original documents or copy thereof.

1. Name of conveying parties: Mizuki SEGAWA;  
Masatoshi ARAI;  
Toshiki YABU; and  
Shunsuke KUGO

Additional name(s) of conveying party(ies) attached? ( ) Yes (X) No

2. Name and address of receiving party(ies):  
Name: Matsushita Electric Industrial Co., Ltd.  
Street Address: 1006, Oaza Kadoma-shi City: Osaka  
State: Country: Japan Zip/Postal Code: 571-8501

Additional name(s) & addresses(es) attached? \_\_\_ Yes X No

3. Name of Conveyance:  
(X) Assignment ( ) Merger ( ) Security Agreement  
( ) Change of Name ( ) Other

Assignment Execution Date: July 13, 2000

4. Application number(s) or patent number(s): 09/551,542

If this document is being filed together with a new application, the execution date of the application is: \_\_\_.

A: Patent Application No.(s)  
B: Patent No.(s)

Title: FREQUENCY CONVERTER

Additional numbers attached? \_\_\_ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:

08/25/2000 WKOR:MA 00000030 09551542  
04 FC:581

40.00 0P

**NIXON PEABODY LLP**  
8180 Greensboro Drive, Suite 800  
McLean, Virginia 22102

6. Total number of applications and patents involved: One (1)

7. Total fee (37 C.F.R. § 3.41) of \$40.00 is enclosed.

8. Deposit Account Number: **19-2380** (Attach duplicate copy of this page if paying by deposit account)

**DO NOT USE THIS SPACE**

9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Eric J. Robinson, Reg. No. 38,285

Signature

8-23-00

Date

Total number of pages comprising cover sheet, attachments and document: Three (3)

## ASSIGNMENT

WHEREAS, Mizuki SEGAWA, Masatoshi ARAI, Toshiki YABU, Shunsuke KUGO  
(hereinafter designated as the undersigned) has (have) invented certain new and useful  
improvements in METHOD OF FABRICATING SEMICONDUCTOR DEVICE  
\_\_\_\_\_ for which the undersigned has (have):

- (a) filed an application for Letters Patent of the United States of America on  
April 18, 2000 having Serial No. 09/551,542; or
- (b) executed an application for Letters Patent of the United States of America on the  
date(s) indicated below; and

WHEREAS, Matsushita Electronics Corporation of  
1-1, Saiwai-cho, Takatsuki-shi, Osaka 569-1193, Japan  
its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee)  
is desirous of acquiring the entire right, title and interest in and to said invention and in and to  
any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the  
undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and  
valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these  
presents do sell, assign and transfer unto the Assignee the full and exclusive right to the said  
invention in the United States of America and its territories and for all foreign countries,  
dependencies and possessions and the entire right, title and interest in and to the application and  
any and all Letters Patent(s) which may be granted therefor in the United States of America and  
its territories, dependencies and possessions, and in and to any and all divisions, reissues,  
continuations and extensions thereof for the full term or terms for which the same may be  
granted.

The undersigned agree(s) to execute all papers necessary in connection with this  
application and any continuing, divisional or reissue applications thereof and also to execute  
separate assignments in connection with such applications as the Assignee may deem necessary  
or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any  
interference which may be declared concerning this application or any continuation, division or  
reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the  
Assignee in every way possible in obtaining and producing evidence and proceeding with such  
interference.

The undersigned agree(s) to execute all papers and documents and to perform any act  
which may be necessary in connection with claims under or provisions of the International  
Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to the Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

This Assignment has been executed by the undersigned on the date(s) indicated.

Date: July 13, 2000, Mizuki Segawa  
**Mizuki SEGAWA**

Date: July 13, 2000, Masatoshi Arai  
**Masatoshi ARAI**

Date: July 13, 2000, Toshiki Yabu  
**Toshiki YABU**

Date: July 13, 2000, Shunsuke Kugo  
**Shunsuke KUGO**

Date: \_\_\_\_\_, \_\_\_\_\_

Date: \_\_\_\_\_, \_\_\_\_\_

Date: \_\_\_\_\_, \_\_\_\_\_

Date: \_\_\_\_\_, \_\_\_\_\_